

The following Listing of Claims will replace all prior versions, and listings, of claims in the application.

**LISTING OF CLAIMS:**

1. (Currently Amended) An electronic circuit board intermediate member comprising:  
  
a plurality of good interposer boards; and  
  
a carrier tape being formed an exfoliate layer,  
  
the good interposer boards being disposed on the carrier tape at every predetermined interval, the good interposer board having a base member mounting an IC chip, extended electrodes being formed on the base member, ~~and each being~~ connected to corresponding a electrode of the IC chip, and an adhesive layer being formed to cover the extended electrode.
  
2. (Previously Presented) A manufacturing method for manufacturing an electronic circuit board intermediate member comprising:  
  
applying adhesive on extended electrodes of an interposer board tape, the interposer board tape being obtained by forming the extended electrodes on a base member, a plurality of IC chips being mounted on the base member, and each of the extended electrodes being connected to corresponding electrode of each of the IC chips;  
  
obtaining individual interposer boards by cutting the interposer board tape, and  
  
selecting only good interposer boards; and

disposing only the interposer boards on a carrier tape at every predetermined interval, the carrier tape being obtained by forming an exfoliate layer on a base tape.

3. (Previously Presented) A manufacturing apparatus for manufacturing an electronic circuit board intermediate member comprising:

first means for applying adhesive on extended electrodes of an interposer board tape, the interposer board tape being obtained by forming the extended electrodes on a base member, a plurality of IC chips being mounted on the base member, and each of the extended electrodes being connected to corresponding electrode of each of the IC chips;

second means for obtaining individual interposer boards by cutting the interposer board tape;

third means for selecting only good interposer boards; and

fourth means for disposing only the interposer boards on a carrier tape at every predetermined interval, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape.

4. (Previously Presented) A manufacturing method for manufacturing non-contact ID card and the like comprising:

peeling an interposer board from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, the interposer board being obtained by

mounting an IC chip, by forming extended electrodes each connected to a corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape; and

depressing the interposer board to an antenna circuit board tape to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.

5. (Previously Presented) A manufacturing apparatus for manufacturing non-contact ID card and the like comprising:

means for peeling an interposer board one by one from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, each interposer board being obtained by mounting an IC chip, by forming extended electrodes each connected to corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape; and

means for depressing the interposer board to an antenna circuit board tape to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.